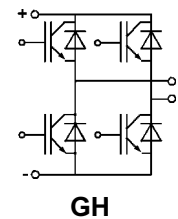
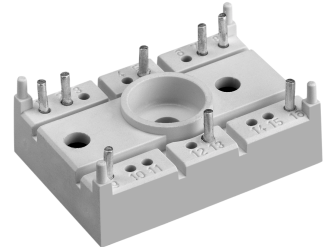


SEMITOP® 2 IGBT Module

SK 20 GH 123



Absolute Maximum Ratings		Values	Units
Symbol	Conditions ¹⁾		
V_{CES}		1200	V
V_{GES}		± 20	V
I_C	$T_h = 25/80\text{ °C}$	23 / 15	A
I_{CM}	$t_p < 1\text{ ms}; T_h = 25/80\text{ °C}$	46 / 30	A
$I_F = -I_C$	$T_h = 25/80\text{ °C}$	24 / 17	A
$I_{FM} = -I_{CM}$	$t_p < 1\text{ ms}; T_h = 25/80\text{ °C}$	48 / 34	A
T_j		$-40 \dots +150$	°C
T_{stg}		$-40 \dots +125$	°C
T_{sol}	Terminals, 10 s	260	°C
V_{isol}	AC, 1 min	2500	V

Characteristics		min.	typ.	max.	Units
Symbol	Conditions ¹⁾				
V_{CEsat}	$I_C = 15\text{ A}; T_j = 25\text{ (125) °C}$	—	2,5(3,1)	3,0(3,7)	V
$t_{d(on)}$	$V_{CC} = 600\text{ V}; V_{GE} = \pm 15\text{ V}$	—	35	—	ns
t_r	$I_C = 15\text{ A}, T_j = 125\text{ °C}$	—	45	—	ns
$t_{d(off)}$	$R_{gon} = R_{goff} = 40\text{ }\Omega$	—	250	—	ns
t_f	inductive load	—	70	—	ns
$E_{on} + E_{off}$		—	3,8	—	mJ
C_{ies}	$V_{CE} = 25\text{ V}; V_{GE} = 0\text{ V}, 1\text{ MHz}$	—	1,0	—	nF
R_{thjh} ³⁾	per IGBT	—	—	1,4	K/W
Inverse Diode ²⁾					
$V_F = V_{EC}$	$I_F = 15\text{ A}; T_j = 25\text{ (125) °C}$	—	2,0(1,8)	2,5(2,3)	V
V_{TO}	$T_j = 125\text{ °C}$	—	1,0	1,2	V
r_T	$T_j = 125\text{ °C}$	—	53	73	m Ω
I_{RRM}	$I_F = 15\text{ A}; V_R = 600\text{ V}$	—	16	—	A
Q_{rr}	$di_F/dt = -200\text{ A}/\mu\text{s}$	—	2,7	—	μC
E_{off}	$V_{GE} = 0\text{ V}; T_j = 125\text{ °C}$	—	0,6	—	mJ
R_{thjh} ³⁾	per Diode	—	—	1,7	K/W
Mechanical Data					
M_1	mounting torque	—	—	2,0	Nm
w		—	21	—	g
Case			T 5		

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N channel, homogeneous silicon structure (NPT Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence
- UL recognized, file no. E 63 532

Typical Applications

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS

¹⁾ $T_h = 25\text{ °C}$, unless otherwise specified

²⁾ CAL = Controlled Axial Lifetime Technology (soft and fast recovery)

³⁾ Thermal resistance junction to heatsink

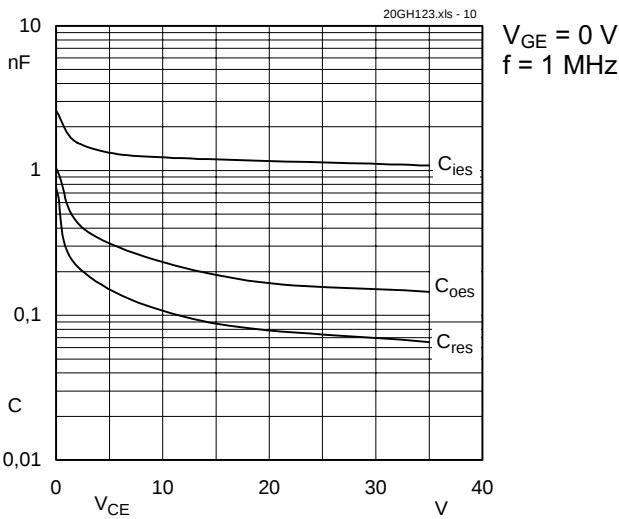
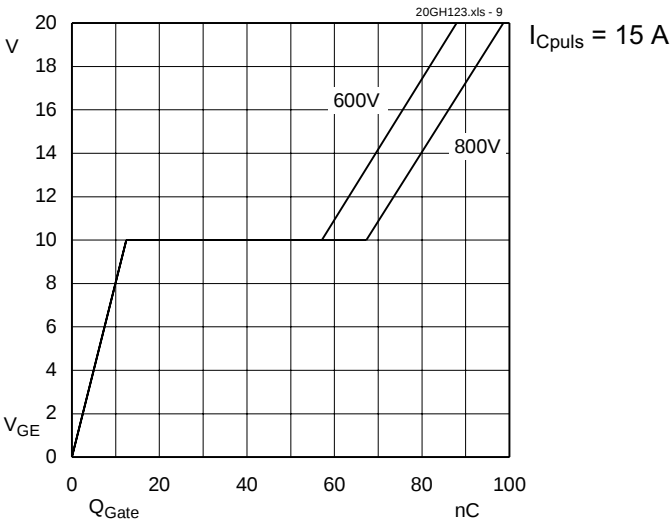
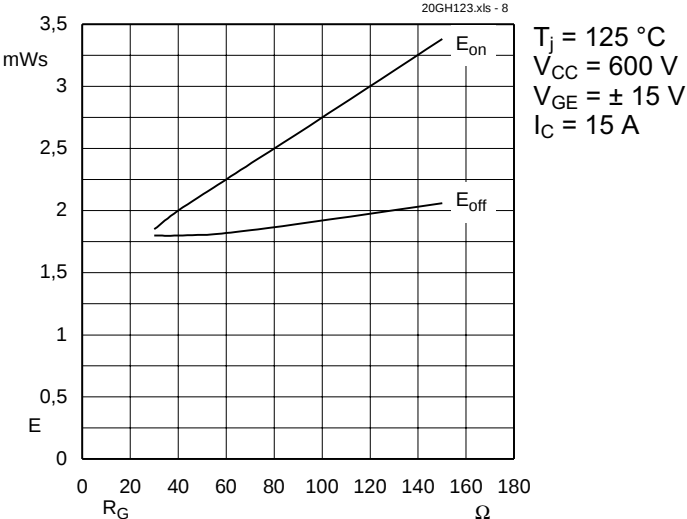
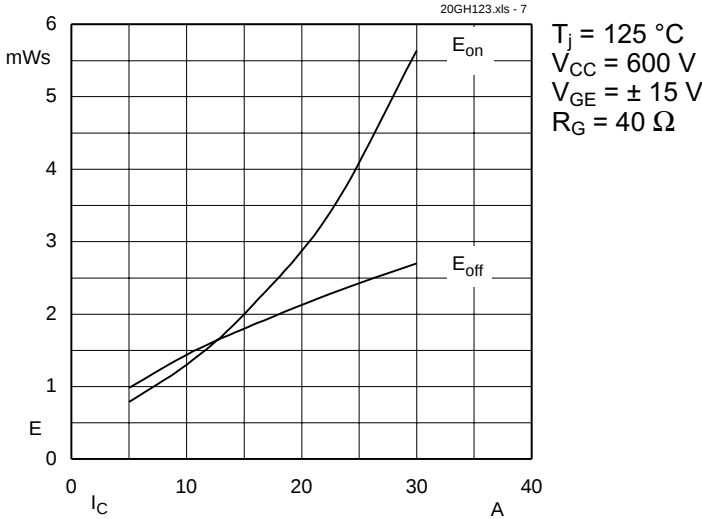
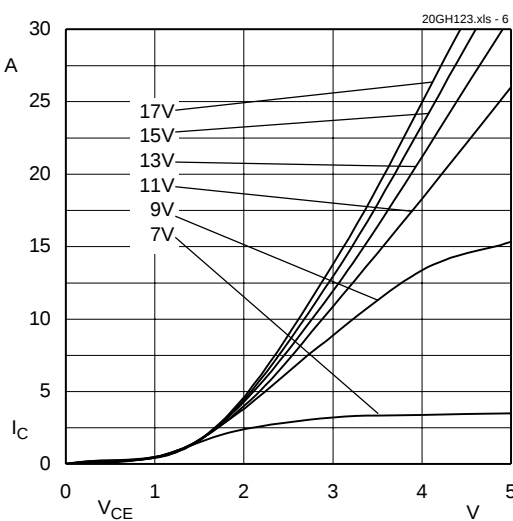
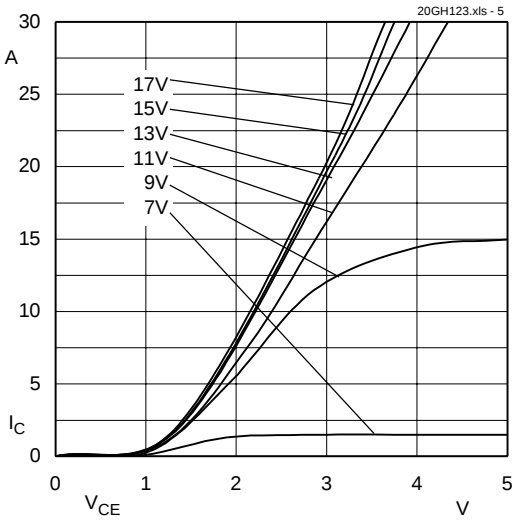


Fig. 9 Typ. gate charge characteristic

Fig. 10 Typ. capacitances vs. V_{CE}

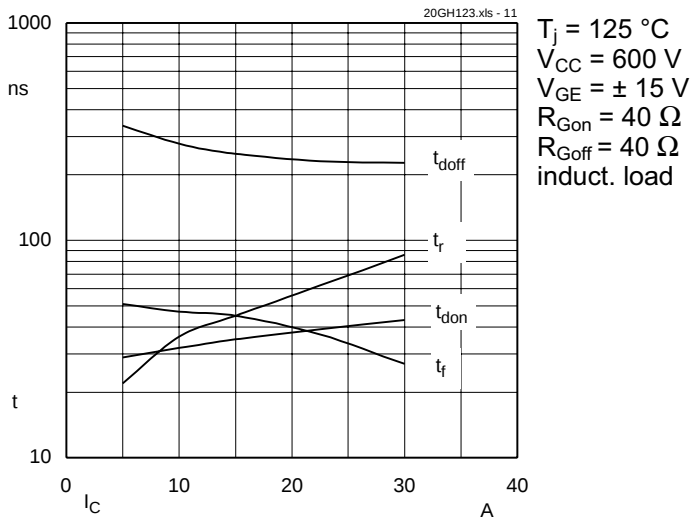


Fig. 11 Typ. switching times vs. I_C

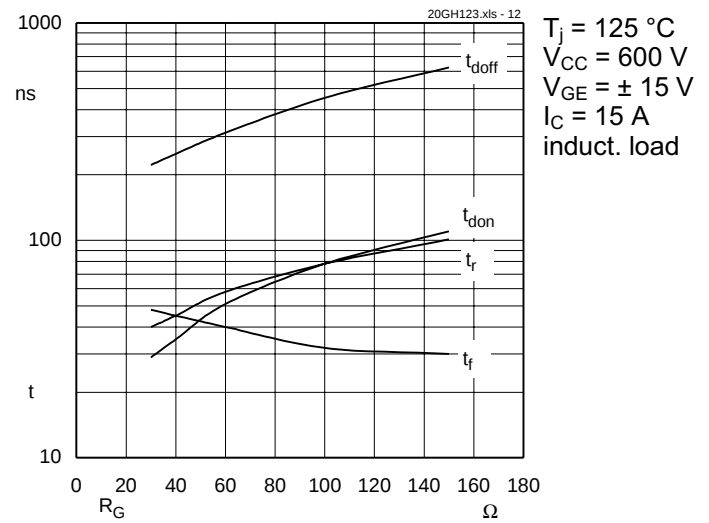


Fig. 12 Typ. switching times vs. gate resistor R_G

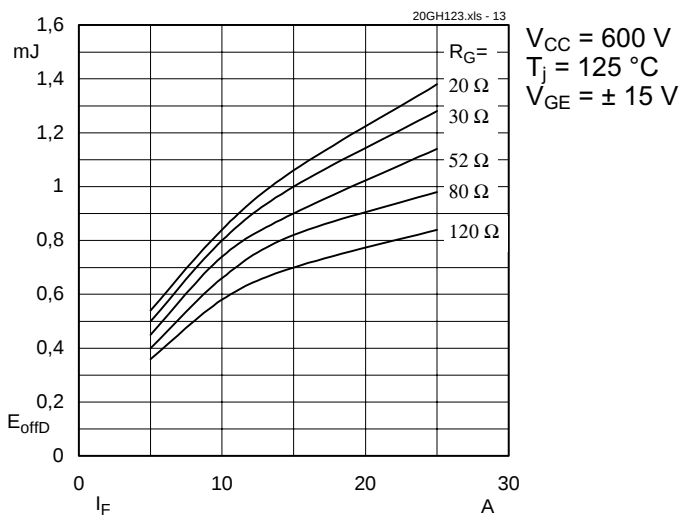
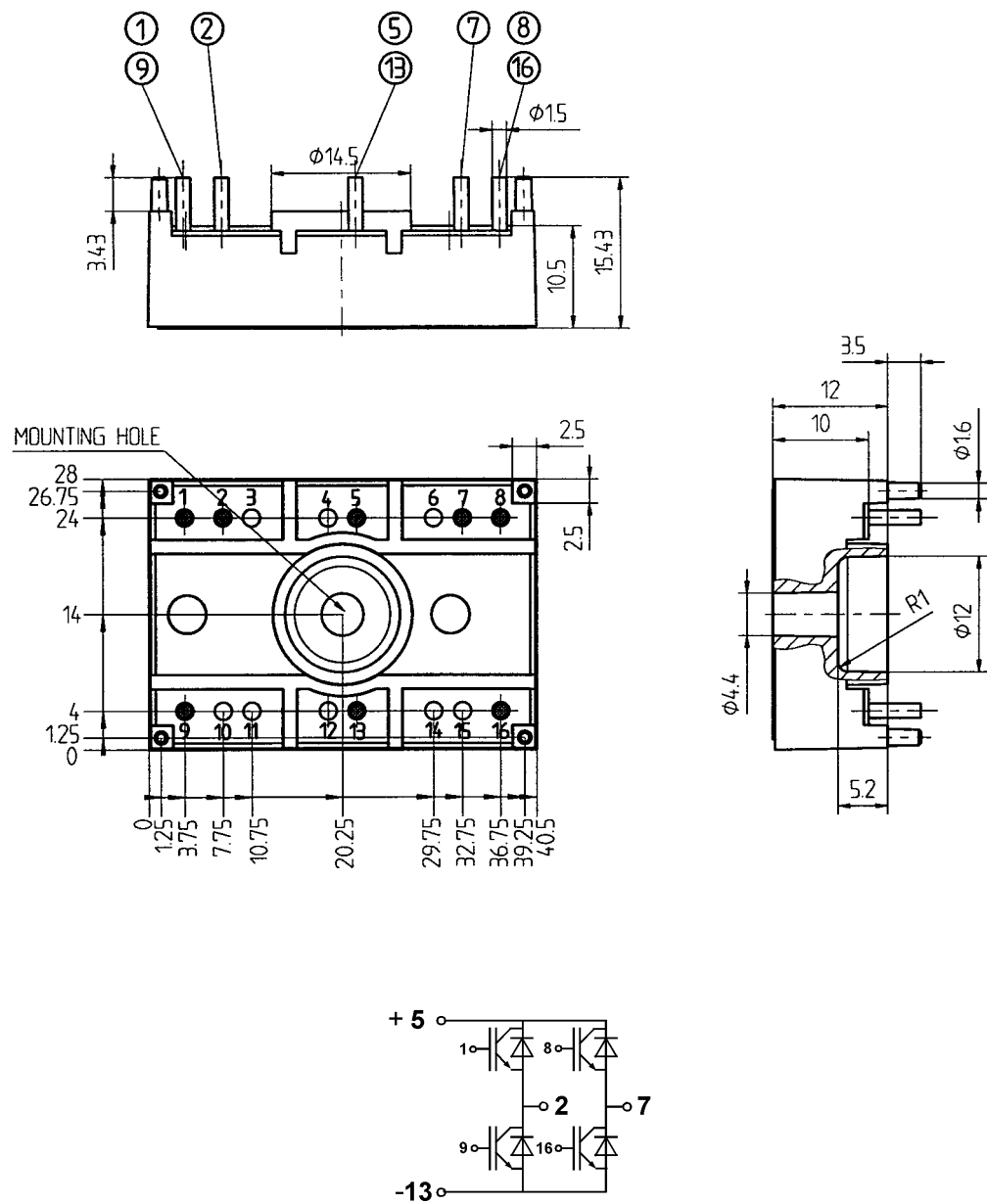


Fig. 13 Diode turn-off energy dissipation per pulse

SEMITOP® 2
SK 20 GH 123

Case T 5



Dimensions in mm

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.